	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	2	"6682981".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	
2	BRS	2	"5869354".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/17 16:19
3	BRS	2	"5354695".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	
4	BRS	2	"5451489".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	1 ' '
5	BRS	2	"6288561".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	' '
6	BRS	2	"5985693".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	
7	BRS		stress near2 (layer membrane) with (device or devices)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	, ,
8	BRS	68	GETAGG NGST/ HISTOR MAMNYSNA!	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	

	Type	Hits		Search Text		DBs	Time	Stamp
	1.		("2915722"	"3202948"			1	
1	•		"3559282"	"3560364"	•			
			"3602982"	"3716429"				
			"3777227"	"3868565"				
			"4070230"	"4131985"				
			"4142004"	"4262631"				
			"4394401"	"4401986"				
			"4416054"	"4539068"				
			"4585991"	"4612083"				
1			"4617160"	"4618397"				
				!!!				
			"4618763"	"4663559"				
			"4693770"	"4702336"				
			"4702936"	"4706166"				
			"4721938"	"4761681"				
			"4784721"	"4810673"				
			"4825277"	"4857481"				
			"4924589"	"4950987"				
			"4952446"	"4957882"				
			"4966663"	"5008619"				
9	BRS	84	"5010024"	"5070026"		US-PGPUB;	2004/	11/17
		_	"5071510"	"5098865"		USPAT; USOCR	17:55	
			"5110373"	"5130894"				
	İ		"5132244"	"5156909"				
			"5203731"	"5236118"				
			"5240458"	"5262351"				
			"5273940"	"5274270"				
1			"5279865"	"5284796"				
		•	"5358909"	"5363021"				
			"5385632"	"5424920"				
			"5426072"	"5426363"				
			"5432444"	"5432729"		·		
			"5434500"	"5457879"				
			"5502667"	"5534465"	•			
			"5580687"	"5581498"				
			"5583688"	"5637536"				
			"5750211"	"5760478"				
			"5793115"	"5856695"				
ļ			"5868949"	"5870176"				
			"5882532" -	"6045625"		-		
			"6084284"	"RE34893").	PN.			
10	BRS	0	("6682981")	.URPN.		USPAT	2004/	11/17
							17:59	
			("4070230"	"4131985"				
11	BRS	8	"4618397"	"4702936"		US-PGPUB;	2004/	12/11
			"4721938"	"4952446"		USPAT; USOCR	22:31	
			"5071510"	<u>"5110373").</u> I	PN.			
12	BRS	19	("5354695")	.URPN.		USPAT	2004/	11/17
<u> </u>			, ===== /				18:00	

13	BRS	6	("4924589" "5420458" "4825277").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/17 18:11
14	BRS	13	("4966663").URPN.	USPAT.	2004/11/26 19:53

	Type	Hits	Search Text	DBs	Time Stamp
15	BRS	99	stress near2 (layer membrane) with dynes	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/26 20:09
16	BRS	1	stress near2 (layer membrane) with fracture with dynes	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/26 20:10
17	BRS	111	stress near2 (layer membrane) with fracture	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 22:02
18	BRS		US-4070230-\$.DID. OR US- 4131985-\$.DID. OR US-4142004-	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 21:30

	Туре	Hits	Search Text	DBs	Time	Stamp
19		58	\$.DID. OR US-4965415-\$.DID. OR US-4966663-\$.DID. OR US-	US-PGPUB;	2004/1	_

	Type	Hits	Search Text	DBs	Time Stamp
20		61	US-5151775-\$.DID. OR US- 5156909-\$.DID. OR US-5203731- \$.DID. OR US-5225771-\$.DID. OR US-0523618-\$.DID. OR US- 5262351-\$.DID. OR US-5270261- \$.DID. OR US-5273940-\$.DID. OR US-5274270-\$.DID. OR US- 5279865-\$.DID. OR US-5284796- \$.DID. OR US-5323035-\$.DID. OR US-5324687-\$.DID. OR US- 5354695-\$.DID. OR US-5363021- \$.DID. OR US-5385632-\$.DID. OR US-5385909-\$.DID. OR US-	'	2004/12/10 21:31

Туре	Hits	Search Text	DBs	Time Stamp
<b>21</b> BRS	1	\$.DID. OR US-5633209-\$.DID. OR US-5637536-\$.DID. OR US-	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	1 ' '

	Туре	Hits	Search Text	DBs	Time Stamp
22	BRS	38	\$.DID. OR US-6020257-\$.DID. OR US-6045625-\$.DID. OR US-	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 21:33
23	BRS	8	S23 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 21:40
24	BRS	20	S24 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/11 22:43
25	BRS	15	S25 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 21:42
26	BRS	17	S26 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 21:42
27	BRS	17	S27 and stress	US-PGPUB;	2004/12/10 21:43
28	BRS	439	stress near2 (layer membrane) with circuit\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 22:12

	Туре	Hits	Search Text	DBs	Time Stamp
29		1289	data adj sink and data adj source		2004/12/10 22:17
30	BRS	854	data adj sink same data adj source	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 22:13
31	BRS	142	data adj sink same data adj source and interconnect		2004/12/10 22:15
32	BRS	1	data adj sink same data adj source and interconnect and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 22:14
33	BRS		data adj sink same data adj source and interconnect and (etch etching etched) with substrate		2004/12/10 22:15
34	BRS	8	data adj sink same data adj source same interconnect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/10 22:15
35	BRS	34	data adj sink same data adj source and interconnect and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 22:16
36	BRS	in 4	data adj sink and data adj source and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/10 22:26
37	BRS	184	data adj sink and data adj source and interconnect	US-PGPUB; USPAT; EPO;	2004/12/10 22:30
38	BRS	35	data adj sink and data adj source and interconnect and substrate	US-PGPUB;	2004/12/10 22:30
39	BRS	340	stress with (deposit depositing deposited) with ((chemical adj vapor) or (RF near2 energy))	US-PGPUB; USPAT; EPO;	2004/12/11 20:38
40	BRS	86	stress near5 (deposit depositing deposited) near5 ((chemical adj vapor) or (RF near2 energy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2004/12/11 20:39

	Туре	Hits	Search Text	DBs	Time Stamp
41	BRS	19867	interconnect and substrate near5 (etch etching etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/11 22:29
42	BRS	2340	interconnect and substrate near5 (etch etching etched) and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/11 22:30
43	BRS	1210	<pre>interconnect and substrate near5 (etch etching etched) and stress with (layer membrane film)</pre>	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/11 22:34
44	BRS	626	<pre>interconnect and substrate near5 (etch etching etched) and stress with (layer membrane film) and (stack stacking stacked)</pre>	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	1 ' '
45	BRS	135	438/6.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:22
46	BRS	3720	438/17.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:22
47	BRS	596	438/53.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:22
48	BRS	329	438/406.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:22
49	BRS	138	438/411.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:22
50	BRS	949 <sup>-</sup>	438/479.ccls.	JPO; DERWENT; IBM_TDB	2004/12/12 22:22
51	BRS	511	438/626.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/12 22:22